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Docket No. 59654 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

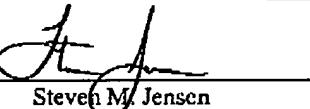
U.S. SERIAL NO: 10/632,709 EXAMINER: H. Trinh

FILED: July 31, 2003 GROUP: 2814

FOR: SEMICONDUCTOR PACKAGE WITH BUILD-UP LAYERS FORMED
ON CHIP AND FABRICATION METHOD OF THE
SEMICONDUCTOR PACKAGE

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on July 17, 2006.

By: 
Steven M. Jensen

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

RESPONSE TO OFFICE ACTION

Applicants are in receipt of the Office Action dated March 15, 2006 of the above-referenced application. A request for a one-month extension of time is submitted herewith. Applicants respond to the Office Action as follows.

Claims 1-20 are pending in the application. Claims 9-20 have been withdrawn from consideration as being directed to non-elected subject matter.

Applicants appreciate the notification of allowable subject matter, i.e., that claims 2-5 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form.